



Physics Colloquium



Thursday, October 8th at 3:30PM in SC 234

Dr. Mario Pacheco

Intel Corporation Inc. and ATTD Failure Analysis Labs

Advanced Imaging Methods for Failure Analysis for Microelectronic Packaging Technologies

The assembly package development roadmap increased interconnect complexity, component density, die stacking, while at the same time reducing critical dimensions; as a result of these trends, the isolation and root cause analysis of defects has become increasingly challenging for traditional analytical tools and techniques. In addition, reduced time-to-information and non-destructive approaches have become critical factors as well. In this presentation we'll review key solutions that have been developed to address some of these analytical gaps in the area of x-ray computed tomography, scanning magnetic microscopy and near-infrared imaging.

Refreshments at 3:00PM in SC 103